

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Xian J. Ning

Attorney Docket: 01 P 7422 US 01

Filed: May 14, 2001

Examiner: TBD

Serial No.: TBD

Art Unit: TBD

For: **Design of Lithography Alignment and Overlay Measurement Marks on CMP Finished Damascene Surface**

11033 U.S. PTO  
09/854760  
05/14/01

INFORMATION DISCLOSURE STATEMENT

Assistant Commissioner For Patents  
Washington, DC 20231

Dear Sir:

MAILING CERTIFICATE

I hereby certify that this correspondence is being deposited with the United States Postal Service as Express Mail No. EL 842426900 US addressed to: Assistant Commissioner for Patents, Washington, DC 20231.

*Karen Fabritius*  
Karen Fabritius

5/14/01  
Date

Applicant wishes to bring to the attention of the Patent and Trademark Office the information noted on the enclosed PTO-1449 that may be considered material to the examination of the above-identified application.

No fee is due at this time as this statement is being filed with the application.

Respectfully submitted,

*Steven H. Slater*  
Steven H. Slater  
Attorney for Applicant  
Reg. No. 35,361

FORM PTO-1449  
(REV. 7-80)

U.S. DEPARTMENT OF COMMERCE  
PATENT AND TRADEMARK OFFICE

ATTY. DOCKET NO.

01 P 7422 US 01

SERIAL NO.

TBD

**LIST OF DOCUMENTS CITED BY APPLICANT**

(Use several sheets if necessary)

APPLICANT

Xian J. Ning

FILING DATE

May 14, 2001

GROUP

TBD

J1033 U.S. PTO  
09/854760  
05/14/01

**U.S. PATENT DOCUMENTS**

*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE (IF APPROPRIATE)
	AA						
	AB						
	AC						
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						
	AJ						
	AK						

**FOREIGN PATENT DOCUMENTS**

		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO
	AL							
	AM							
	AN							

**OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)**

AO	Chi-Tzung Wang, et al., Pad Wear Analysis in CMP; 1999 VMIC Conference; 1999 IMIC 109/99/0267(c)
AP	Srin Raghavan, et al., Electrochemical Behavior of Copper and Tantalum in Silica Slurries Containing Hydroxylamine, 1999 VMIC Conference; 1999 IMIC 109/99/0619(c)
AQ	Rajeev Bajaj, et al., Manufacturability Considerations and Approaches for Development of a Copper CMP Process; 1999 VMIC Conference; 1999 IMIC 109/99/0144(c)